

REMARKS

Claims 1-6, 8, 14-15, 18-20 and 22-27 were examined. No claims are amended. Claims 1-6, 8, 14-15, 18-20 and 22-27 remain in the Application.

The Patent Office finds claims 1-6, 8, 14-15 and 18-22 allowable over the prior art of record. The Patent Office rejects claim 23 under 35 U.S.C. §102(e). The Patent Office rejects claims 24-27 under 35 U.S.C. §103(a). Curiously, the Patent Office also rejects claims 6 and 21 under 35 U.S.C. §103(a), though claims 1 and 14, from which claims 6 and 21, respectively, depend were found allowable. Applicant respectfully requests reconsideration of the pending claims in view of the following remarks.

A. 35 U.S.C. §102(e): Rejection of Claim 23

The Patent Office rejects claim 23 under 35 U.S.C. §102(e) as anticipated by U.S. Patent Application No. 2002/0001688 of Ueda et al. (Ueda). According to the Patent Office, Ueda discloses applying an adhesive layer 2 to a wafer surface 1 and immediately applying a backing film 3 to the adhesive layer.

Paragraphs 0047-0051 of Ueda describe various embodiments of applying a releasing plastic film on a sheet resin composition. Each of these embodiments deals with the pre-loading of the sheet resin composition and the releasing plastic film (i.e., before the sheet resin composition is applied to a wafer surface). None of the embodiments deal with putting a releasing plastic film on a sheet resin composition after the sheet resin composition is applied to a wafer surface. Similarly, paragraphs 0053-0063 describe a process for manufacturing a semiconductor device including placing sheet resin composition 2 onto wafer 1, the sheet resin composition having both sides protected with releasing plastic films. (See, e.g., ¶0055.) Ueda does not describe applying an adhesive to a wafer surface to form an adhesive layer and, following applying the adhesive layer, applying a backing film to the adhesive layer. It may be that an apparatus of Ueda and apparatus formed according to the method of claim 23 may be similar, but the method by which claim 23 forms its apparatus is what is claimed and is not described by Ueda. Applicant respectfully requests that the Patent Office withdraw the objection to claim 23 under 35 U.S.C. §102(e).

B. 35 U.S.C. §103(a): Rejection of Claims 24-26

The Patent Office rejects claims 24-26 under 35 U.S.C. §103(a) as obvious over Ueda in view of U.S. Patent Application No. 2002/0161100 of Kojima et al. (Kojima). Ueda is cited for its teachings with respect to claim 23 and Kojima is cited for describing a double-bumped wafer, and applying an adhesive by a pressure roller.

Claims 24-26 depend from claim 23 and therefore contains all the limitations of that claim. Claims 24-26 are not obvious over the cited references, because the cited references fail to disclose or provide any motivation for applying an adhesive to a wafer surface to form an adhesive layer and, following applying the adhesive layer, applying a backing film to the adhesive layer. Ueda is cited for teaching these operations. As noted above with respect to claim 23, however, Ueda fails to disclose applying a backing film to an adhesive layer following the application of the adhesive layer to a wafer surface. Kojima does not cure the defects of Ueda.

Applicant respectfully requests the Patent Office withdraw the rejection to 24-26 under 35 U.S.C. §103(a).

C. 35 U.S.C. §103(a): Rejection of Claim 6, 21 & 27

The Patent Office rejects claims 6, 21 and 27 under 35 U.S.C. §103(a) as obvious over Ueda and Kojima and further in view of U.S. Patent Application No. 2003/0180987 of Milla et al. (Milla). Milla is cited for disclosing the use a dual blade to dice a wafer.

With respect to claims 6 and 21, Applicant believes the claims are included in error, since the independent claims (claims 1 and 14) from which they depend are found to be allowable. Therefore, Applicant does not provide an argument with respect to the obviousness of these claims.

Claim 27 depends from claim 23 and therefore contains all the limitations of that claim. Claim 27 is not obvious over the cited references, because the cited references fail to describe or provide any motivation for applying an adhesive layer to a wafer surface following the formation of an adhesive layer on a wafer surface.

Applicant respectfully requests that the Patent Office withdraw the rejection of claims 6, 21 and 27 under 35 U.S.C. §103(a).

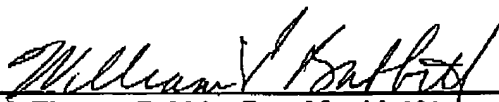
CONCLUSION

In view of the foregoing, it is believed that all claims now pending patentably define the subject invention over the prior art of record and are in condition for allowance, and such action is earnestly solicited at the earliest possible date. If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2666 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17, particularly, extension of time fees. If a telephone interview would expedite the prosecution of this Application, the Examiner is invited to contact the undersigned at (310) 207-3800.

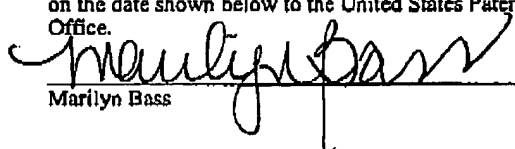
Respectfully submitted,

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I hereby certify that this correspondence is being transmitted by facsimile on the date shown below to the United States Patent and Trademark Office.

Marilyn Bass March 7, 2006